

ABOUT ME

I am an enthusiastic SoC Researcher, with Physical Design expertise and a keen eye for design methodologies. I thrive in contexts where "what?" is always followed by "how?". Currently, I am looking for a chance to boost my knowledge on Computer Architectures while leveraging my expertise in SoC design. My ambition is to steer the semiconductor industry towards the path of Architecture-Design Co-Optimization, as I strongly believe that it will be a key enabler for next generation digital ICs.

EXPERIENCE

Chiplet Solution Architect

IMEC

- 📅 Sep 2023 – Present 📍 Leuven, BE
- Drive system architecture development with 2.5D and 3D technologies
 - Next generation HPC systems for AI

Researcher

IMEC

- 📅 Nov 2021 – August 2023 📍 Leuven, BE
- Backside PDN and functional Backside pathfinding
 - HW-SW co-design methodologies for STCO

Doctoral Researcher

Cadence Design Systems - IMEC

- 📅 Oct 2018 – 2021 📍 Leuven, BE
- Proposal and implementation of new methods to enable DTCO and 3D IC design
 - European project technical lead for 2nm technology node research

Engineering Internship

Huawei Technologies

- 📅 Feb 2018 – Jul 2018 📍 Sophia-Antipolis, FR
- Architecture design and physical implementation of digital filters for All Digital PLLs

EDUCATION

Doctor of Philosophy (PhD), Electrical Engineering

Ecole polytechnique de Bruxelles – Université Libre de Bruxelles - IMEC

- 📅 Oct 2018 – June 2022 📍 Leuven, BE
- Thesis: "Design Enablement of integrated circuits using sub-5nm technology process and 3D integration"
 - Guest lecturer - ETH Zurich, Politecnico di Bari

MSc, Electrical Engineering, Micro Electronics Systems

Dipartimento di Ingegneria Elettrica e dell'informazione – Politecnico di Bari

- 📅 Jan 2016 – Jul 2018 📍 Bari, IT
- Feb-July 2017 - Exchange semester at Technology University of Eindhoven (TUE) in the Electronic Systems group (ES)

TECHNICAL SKILLS

TCL
Bash
Linux
Verilog, VHDL
Python
Git
Matlab



SOFT SKILLS

Problem-solving
Project/People management
Mentoring
Empathy
Affinity to learn
Team player
Public Speaking/Presenting

LANGUAGES

Italian
English
French
Dutch



AWARDS

🏆 ERASMUS+ for Traineeship
Scholarship

TUCEP

📅 2018 📍 Bari, IT

🏆 ERASMUS+ Scholarship

Politecnico di Bari

📅 2017 📍 Bari, IT

INTERESTS

Videogames
Board/Card games
eSports
Soccer
Cinema
Travel
Music
Photography

LIST OF PUBLICATIONS

- **G.Sisto**, et al., "Block-level Evaluation and Optimization of Backside PDN for High-Performance Computing at the A14 node", 2023 IEEE Symposium on VLSI Technology and Circuits, Kyoto, Japan
- **G.Sisto**, et al., "System-level evaluation of 3D power delivery network at 2nm node", 2023 SPIE Advanced Lithography + Patterning, DTCO and Computational Patterning, San Jose, USA
- **G.Sisto**, et al., "Physical design level PPA evaluation of buried power rail at 2nm node", 2023 SPIE Advanced Lithography + Patterning, DTCO and Computational Patterning, San Jose, USA
- **G.Sisto**, et al., "Evaluation of Nanosheet and Forksheet Width Modulation for Digital IC Design in the Sub-3nm Era", IEEE Transactions on Very Large Scale Integration (VLSI) Systems, vol. 30, no. 10, pp. 1497-1506, Oct. 2022
- R.Chen, **G.Sisto***, et al., "Design and Optimization of SRAM Macro and Logic Using Backside Interconnects at 2nm Node", IEDM 2021, San Francisco, USA (*authors contributed equally to the work)
- **G.Sisto** et al., "Design And Sign-off Methodologies For Wafer-To-Wafer Bonded 3D-ICs At Advanced Nodes (invited)", SLIP 2021 (co-hosted with ICCAD 2021), Virtual Event
- **G.Sisto** et al., "IR-Drop Analysis of Hybrid Bonded 3D-ICs with Backside Power Delivery and μ - & n - TSVs", IITC 2021, Virtual Event
- **G.Sisto** et al., "Design enablement of fine pitch face-to-face 3D system integration using die-by-die place & route", 3DIC 2019, Sendai, Japan